SOLID STATE OPTRONICS

TDM3052

Random Phase Switching
600V
Triac Driver

Description

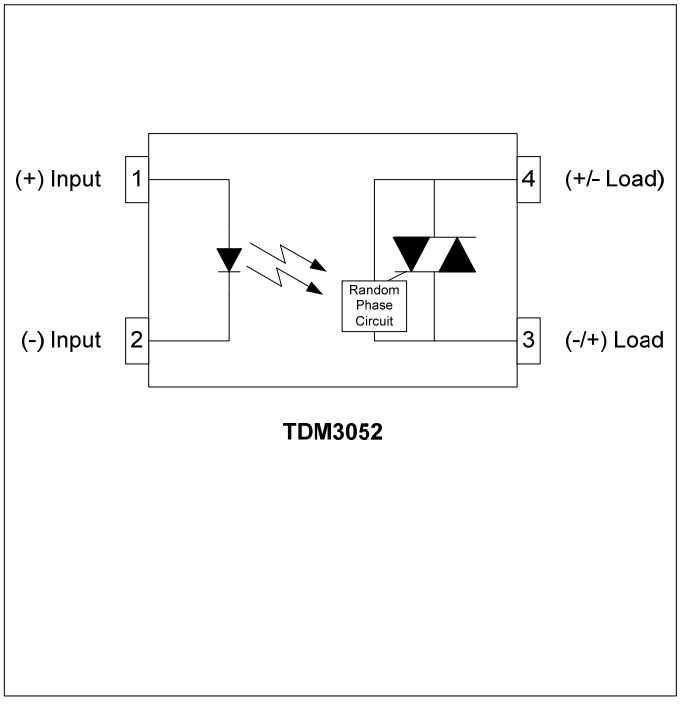
The TDM3052 consists of a GaAs LED optically coupled to a Random Phase photo-sensitive Triac Driver chip. The miniature 4 pin SOP package provides high input-to-output isolation and drives high powered triacs while using very little board space. Typical uses include interfacing logic level control signals to equipment powered from $110V_{AC}$ to $240V_{AC}$ lines.

The TDM3052 comes standard in a miniature 4 pin SOP package.

Applications

- Home Appliances
- Motor / Drive Controls
- Solid State Relays
- High Power Triacs
- Dimmer Controls

Schematic Diagram



TDM3052

Features

- Ultra Miniature 4-Pin Small Outline Package
- Random Phase Switching
- 600V Blocking Voltage
- Low Trigger Current (10mA MAX)
- High Input-to-Output Isolation ($3.75kV_{RMS}$)
- Long Life / High Reliability
- RoHS / Pb-Free / REACH Compliant

Agency Approvals

UL / C-UL:	File # E201932
VDE:	File # 40035191 (EN 60747-5-2)

Absolute Maximum Ratings

The values indicated are absolute stress ratings. Functional operation of the device is not implied at these or any conditions in excess of those defined in electrical characteristics section of this document. Exposure to absolute Maximum Ratings may cause permanent damage to the device and may adversely affect reliability.

Storage Temperature	-55 to +125°C
Operating Temperature	-40 to +100°C
Continuous Input Current	50mA
Transient Input Current	500mA
Reverse Input Control Voltage	5V
Input Power Dissipation	70mW
Total Power Dissipation	170mW
Solder Temperature – Wave (10sec)	260°C
Solder Temperature – IR Reflow (10sec)	260°C

Ordering Information

Part Number	Description
TDM3052	4 pin SOP, (100/Tube)
TDM3052-TR	4 pin SOP, Tape and Reel (2000/Reel)

NOTES: Suffixes listed above are not included in marking on device for part number identification

© 2013 Solid State Optronics • San José, CA

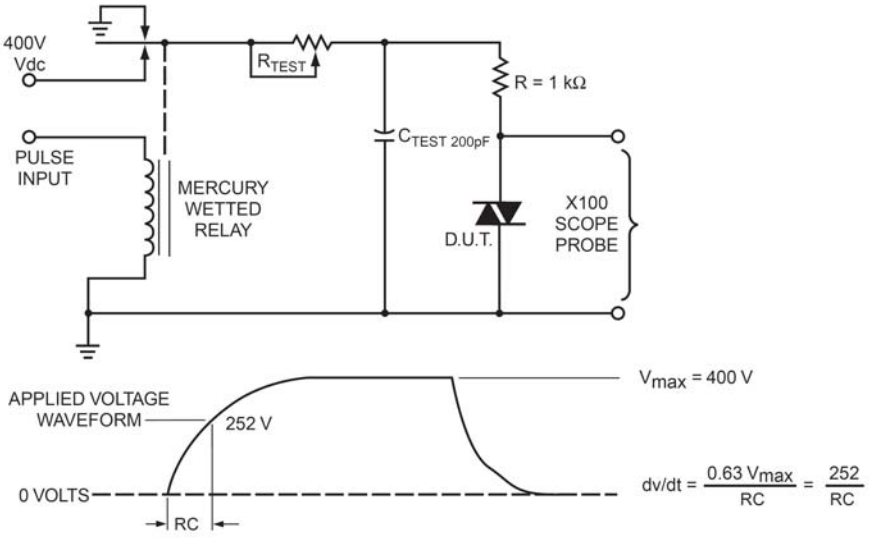
Electrical Characteristics, T_A = 25°C (unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Input Specifications						
LED Forward Voltage	V_F	-	1.4	1.8	V	I_F = 10mA
LED Reverse Voltage	BV_R	5	-	-	V	I_R = 10µA
Reverse Leakage Current	$I_{InRleak}$	-	-	10	µA	V_R = 5µA
Trigger Current[1]	I_{FT}	-	-	10	mA	Main Terminal Voltage = 3V
Output Specifications						
Blocking Voltage	V_{DRM}	600	-	-	V	I_O = 1µA
Peak Blocking Current	I_{DRM1}	-	10	100	nA	V_{DRM} = 600
Continuous Load Current	I_O	-	-	70	mA	I_F = 10mA
On-State Voltage	V_{ON}	-	2	3	V	I_F = 10mA, I_{TM} = 70mA
Leakage Current	I_{DRM2}	-	0.2	1	µA	I_F=0mA, V_{DRM} = 600V
Holding Current	I_{HOLD}	-	250	-	µA	-
Critical Rate of Rise[2]	dV/dt	1,000	1,500	-	V/µS	-
Isolation Specifications						
Isolation Voltage	V_{ISO}	3,750	-	-	V_{RMS}	RH ≤ 50%, t=1min
Input-Output Resistance	R_{I-O}	-	10^{12}	-	Ω	V_{I-O} = 500V_{DC}

Note 1: Resistive load. For inductive loads, higher drive current is recommended

Note 2: This is for static dV/dt. Test Circuit Below

TDM3052 Static dV/dt Test Circuit:



TDM3052 Performance & Characteristics Plots, T_A = 25°C (unless otherwise specified)

Figure 1: *Maximum Load Current vs. Temperature*

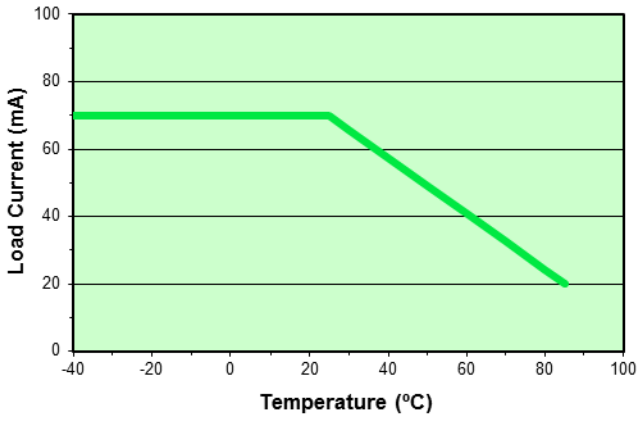


Figure 2: *Typical Blocking Voltage Distribution* (N = 100, Ta = 25°C)

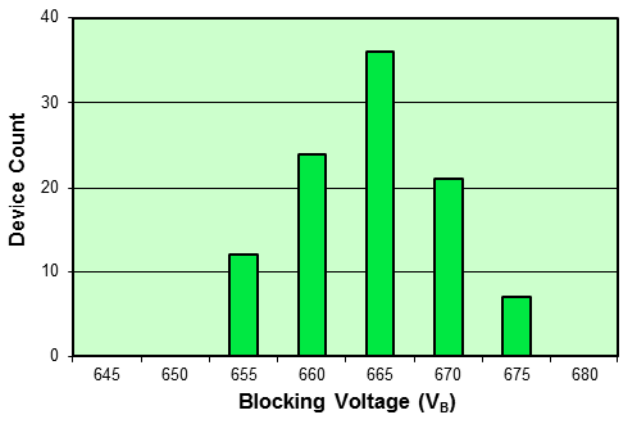


Figure 3: *On State Characteristics*

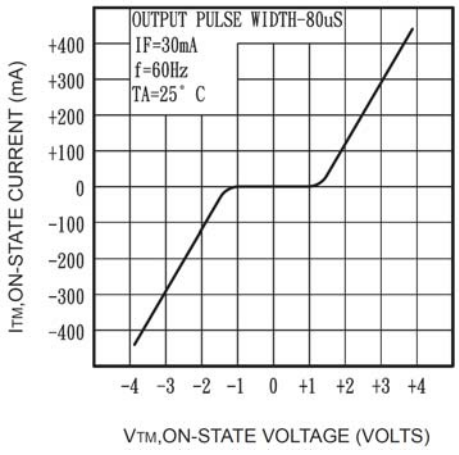


Figure 4: *Peak Blocking Current (I_{DRM1}) vs. Temperature (°C)*

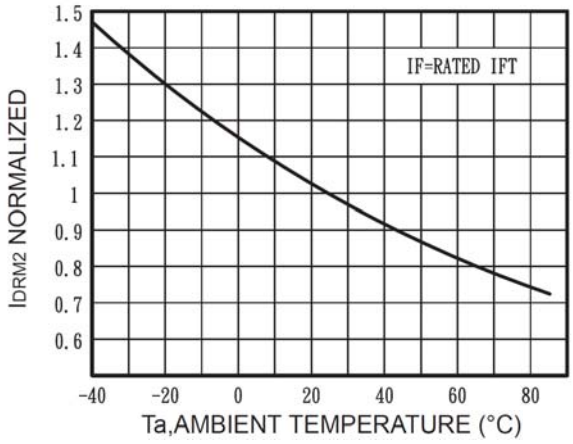
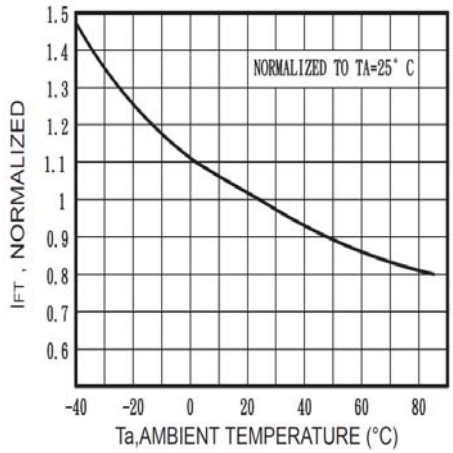


Figure 5: *Trigger Current (I_{FT}) vs. Temperature (°C)*

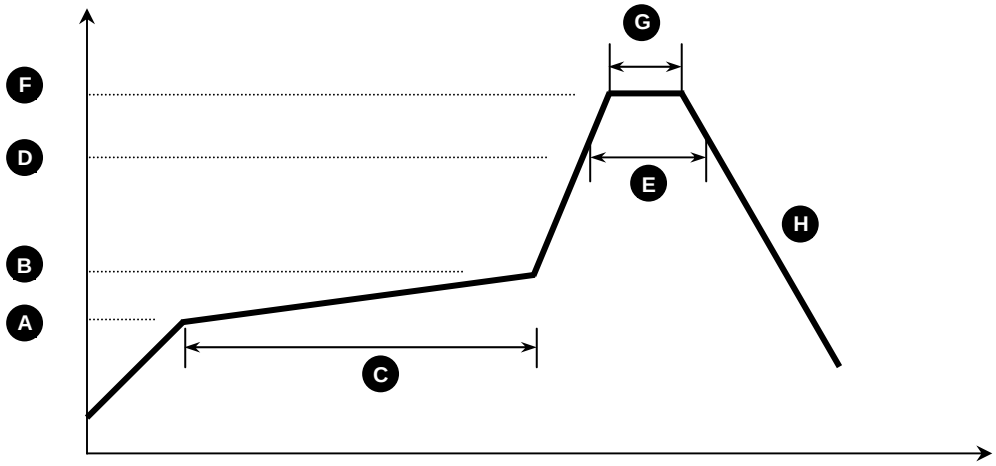


© 2013 Solid State Optronics • San José, CA

TDM3052 Solder Reflow Temperature Profile Recommendations

(1) *Infrared Reflow:*

Refer to the following figure as an example of an optimal temperature profile for single occurrence infrared reflow. Soldering process should not exceed temperature or time limits expressed herein. Surface temperature of device package should not exceed 250ºC:



Process Step	Description	Parameter
A	Preheat Start Temperature (ºC)	150ºC
B	Preheat Finish Temperature (ºC)	180ºC
C	Preheat Time (s)	90 - 120s
D	Melting Temperature (ºC)	230ºC
E	Time above Melting Temperature (s)	30s
F	Peak Temperature, at Terminal (ºC)	260ºC
G	Dwell Time at Peak Temperature (s)	10s
H	Cool-down (ºC/s)	<6ºC/s

(2) *Wave Solder:*

Maximum Temperature:	260ºC (at terminal)
Maximum Time:	10s
Pre-heating:	100 - 150ºC (30 - 90s)
Single Occurrence	

(3) *Hand Solder:*

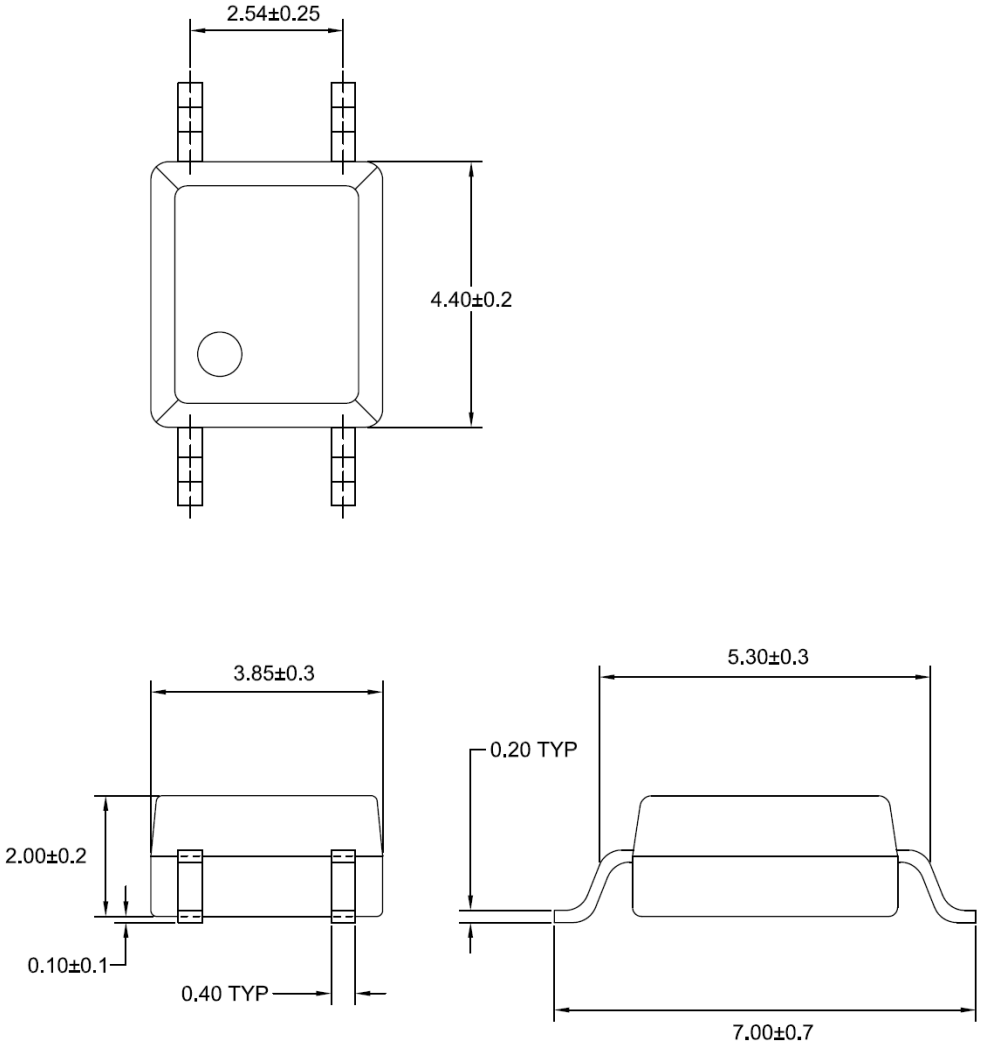
Maximum Temperature:	350ºC (at tip of soldering iron)
Maximum Time:	3s
Single Occurrence	

© 2013 Solid State Optronics • San José, CA

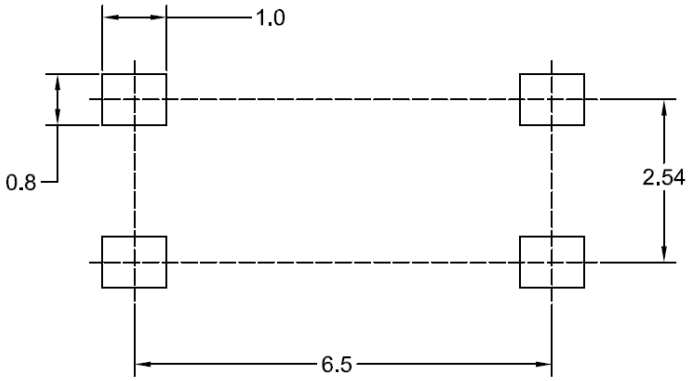
TDM3052 Package Dimensions

4 PIN SOP Package

Note: *All dimensions in millimeters [mm]*



4 PIN SOP Footprint

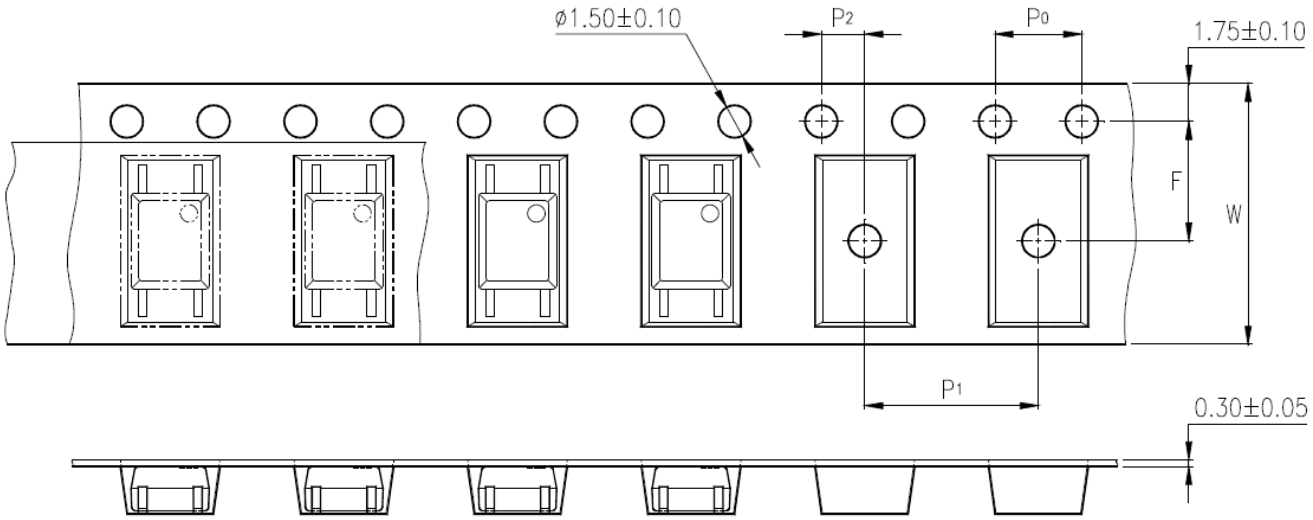


© 2013 Solid State Optronics • San José, CA

TDM3052 Packaging Specifications

Tape & Reel Specifications (T&R)

Note: *All dimensions in millimeters [mm]*



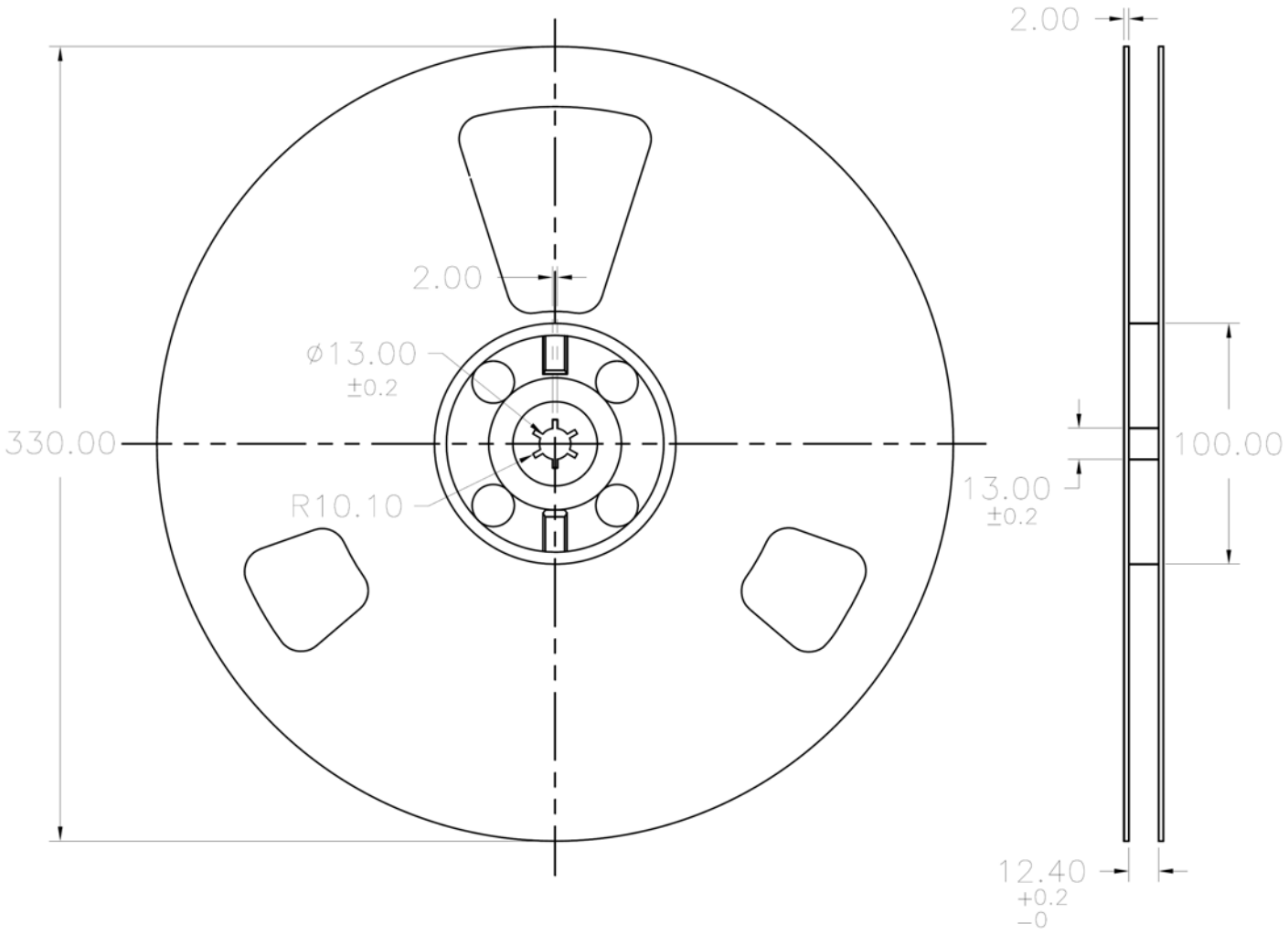
Specification	Symbol	Dimensions, mm (inches)
Tape Width	W	12 ± 0.3 (0.47)
Sprocket Hole Pitch	P0	4 ± 0.1 (0.15)
Compartment Location	F P2	5.5 ± 0.1 (0.217) 2 ± 0.1 (0.079)
Compartment Pitch	P1	8 ± 0.1 (0.315)

© 2013 Solid State Optronics • San José, CA

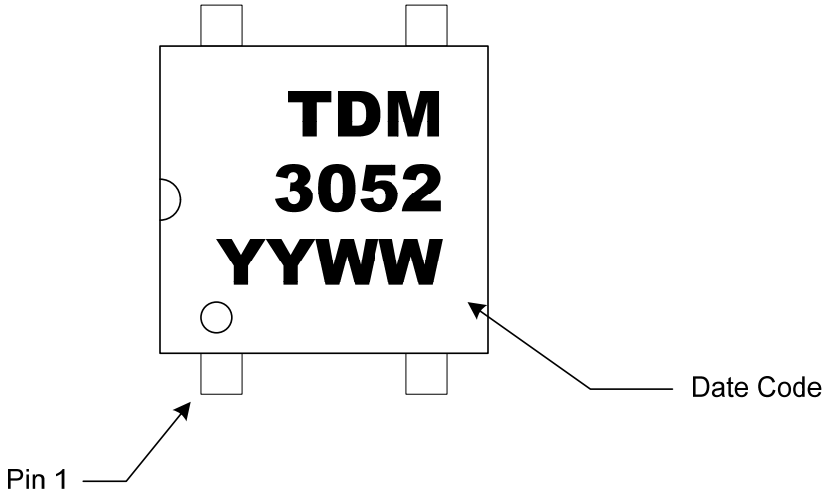
TDM3052 Packaging Specifications

Tape & Reel Specifications (T&R)

Note: *All dimensions in millimeters [mm*



TDM3052 Package Marking



TDM3052 Package Weights

Device	Single Unit	Full Tube (100pcs)	Full Pouch (10 tubes)	Full Reel (2000pcs)
TDM3052	0.10	23	240	-
TDM3052-TR	0.10	-	-	500

Note: *All weights above are in GRAMS, and include packaging materials where applicable*

DISCLAIMER

Solid State Optronics (SSO) makes no warranties or representations with regards to the completeness and accuracy of this document. SSO reserves the right to make changes to product description, specifications at any time without further notices.
SSO shall not assume any liability arising out of the application or use of any product or circuit described herein. Neither circuit patent licenses nor indemnity are expressed or implied.
Except as specified in SSO's Standard Terms & Conditions, SSO disclaims liability for consequential or other damage, and we make no other warranty, expressed or implied, including merchantability and fitness for particular use.

LIFE SUPPORT POLICY

SSO does not authorize use of its devices in life support applications wherein failure or malfunction of a device may lead to personal injury or death. Users of SSO devices in life support applications assume all risks of such use and agree to indemnify SSO against any and all damages resulting from such use. Life support devices are defined as devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when used properly in accordance with instructions for use can be reasonably expected to result in significant injury to the user, or (d) a critical component of a life support device or system whose failure can be reasonably expected to cause failure of the life support device or system, or to affect its safety or effectiveness.